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(71) Applicant: **CABOT MICROELECTRONICS CORPORATION** [US/US]; 870 North Commons Drive, Aurora, IL 60504 (US).

(72) Inventors: **DE REGE THESAURO, Francesco**; c/o Legal Department, Cabot Microelectronics Corp., 870 North Commons Drive, Aurora, IL 60504 (US). **BRUSIC, Vlasta**; c/o Legal Department, Cabot Microelectronics Corp., 870 North Commons Drive, Aurora, IL 60504 (US). **BAYER, Benjamin, P.**; c/o Legal Department, Cabot Microelectronics Corp., 870 North Commons Drive, Aurora, IL 60504 (US).

(74) Agents: **WESEMAN, Steven** et al.; Associate General Counsel, Intellectual Property, Cabot Microelectronics Corporation, 870 North Commons Drive, Aurora, IL 60504 (US).

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(54) Title: CHEMICAL-MECHANICAL POLISHING OF METALS IN AN OXIDIZED FORM

(57) Abstract: The invention provides a method for polishing a substrate comprising a metal in an oxidized form, the method comprising the steps of: (a) providing a substrate comprising a metal in an oxidized form, (b) contacting a portion of the substrate with a chemical-mechanical polishing system comprising: (i) a polishing component, (ii) a reducing agent, and (iii) a liquid carrier, and (c) abrading at least a portion of the metal in an oxidized form to polish the substrate. The reducing agent can be selected from the group consisting of 3-hydroxy-4-pyrones, α-hydroxy-γ-butyrolactones, ascorbic acid, borane, borohydrides, dialkylamine boranes, formaldehyde, formic acid, hydrogen, hydroquinones, hydroxylamine, hypophosphorous acid, phosphorous acid, a metal or metal ions in an oxidation state having a standard redox potential that is less than the standard redox potential of the metal in an oxidized form, trihydroxybenzenes, solvated electrons, sulfurous acid, salts thereof, and mixtures thereof.

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